

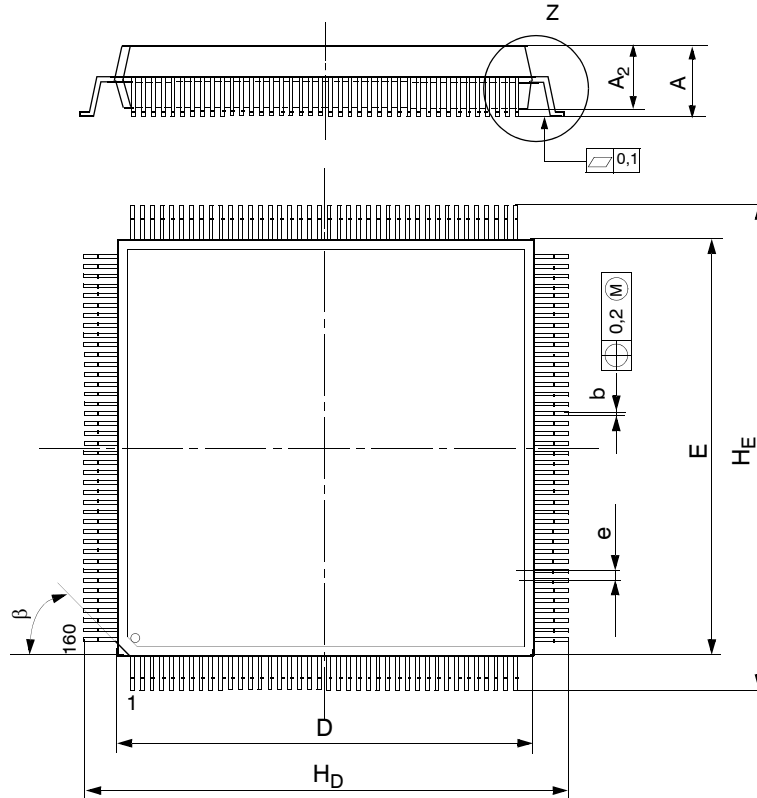
	Package PQFP160 (28x28)	MDS 721
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Supersedes
Edition 11.95

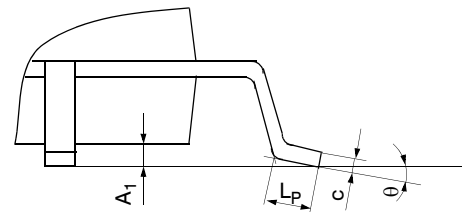
Dimensions in millimetres

Based on JEDEC JEP95: MO-112 DD-1

Dimensions



Detail Z



Dimensions of Sub-Group B1	
e_{nom}	0,65
A_{max}	4,00
b_{Pmin}	0,22
b_{Pmax}	0,38
H_{Emin}	31,65
H_{Emax}	32,15
H_{Dmin}	31,65
H_{Dmax}	32,15
L_{Pmin}	0,63

- Weight** $\leq 5,4 \text{ g}$
- Package Body Material** Low Stress Epoxy
- Lead Material** FeNi-Alloy or Cu-Alloy
- Lead Finish** solder plating
- Lead Form** Z-bends

Dimension of Sub-Group C1	
A_{min}	3,68
A_{1min}	0,25
A_{1max}	0,50
A_{2min}	3,40
A_{2max}	3,60
c_{min}	0,15
c_{max}	0,20
D_{min}	27,90
D_{max}	28,10
E_{min}	27,90
E_{max}	28,10
θ_{min}	0°
θ_{max}	10°
β	45°

Zentrum Mikroelektronik Dresden AG		
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